SPECIFICATION FOR APPROVAL

DESCRIPTION: Pitch 1.00mm ZIF F	FPC Connector, R/A, SMT Type Bottom Contac	·t
CUSTOMER PROD.NO/DWG.NO	D:	
E&T PROD.NO:	6915K-XXXX-XXX	
APPROVAL SHEET NO:		
E&T DWG. NO./DOCUMENT:	6915K-XXXX-XXX	
		DEVI: A A

PLEASE RETURN TO US ONE COPY OF "SPECIFICATION FOR APPROVAL" WITH YOUR APPROVED SIGNATURES.

APPROVED SIGNATURES					



ENTERY INDUSTRIAL CO., LTD.
E&T ELECTRONICS (DONG GUAN) CO., LTD.
E&T ELECTRONICS (SU ZHOU) CO., LTD.
E&T ELECTRONICS (NANKEEN)CO.,LTD.

Title: Pitch 1.00mm ZIF FPC Connector, R/A, SMT Type Bottom Contact

RE2	01305023 01412009 01503002	Title: Pitch 1.00mm ZIF FPC Connector, R/A, S	h 1.00mm ZIF FPC Connector, R/A, SMT Type Bottom Contact				
A4 Rev	2014/2/25 Description		s Document Contains Information That Is Proprietary To T And Should Not Be Used Without Written Permission				
Document No. Prepared By: Hill Chang		Date: 10,13,2008'					
6915K-XXXX-XXX		Checked By:	Date:				

GROUP AND TEST SEQUENCE

	Test of Examination				,	Test	Gr	oup)			
			В	С	D	Е	F	G	Н	I	J	K
1	Examination of Product	1,9	1,6	1,5	1,5	1,5	1,4	1,5	1,3	1,3	1,5	
2	Contact Resistance	2,6	2,5	2,4	2,4	2,4		2,4			2,4	
3	Insulation Resistance	3,7										
4	Dielectric Strength	4,8										
5	FPC Retention Force		3									
6	Terminal / Housing Retention Force											1
7	Durability		4									
8	Vibration			3								
9	Heat Resistance				3							
10	Cold Resistance					3						
11	Humidity	5										
12	Solder Ability						3		2			
13	Resistance To Soldering Heat									2		
14	Steam Aging						2					
15	Salt Spray							3				
16	Temperature Cycling										3	

PRODUCT SPECIFICATION

1. SCOPE:

This specification covers the pitch1.00 mm ZIF FPC connector series.

2. PRODUCT NAME AND PART NUMBER:

Product Name	E&T Part Number
1.00mm ZIF FPC Connector, R/A, SMT Type Bottom Contact	6915K-XXXX-XXX

3. RATINGS:

Item	S	tandard
Rated Voltage (MAX.)	125 V	(AC(rms/DC)
Rated Current (MAX.)	1A	(AC(IIIIs/DC)
Operating Temperature Range	-40 ⁰	C ~ +85 ⁰ C

^{*}Including terminal temperature rise

4.PERFORMANCE:

4-1 Electrical Performance

	Item	Test Condition	Requirement	
4-1-1	Contact Resistance	Test Current: 10 mA Max. Test Voltage: 20mV Max	20 mΩ MAX.	
4-1-2	Insulation Resistance	Test Voltage: 500V DC. Test Duration: 1 minutes. Test Method: MIL-STD-202, method 302	100 MΩ Min.	
4-1-3	Dielectric Strength	Test Voltage:500V AC. Test Time: 60 sec. Test Method: MIL-STD-202, Method 301.	No Breakdown	

4-2 Mechanical Performance

	Item	Test Condition	Requirement	
4-2-1	FPC Retention Force	Test Speed: 25±3 mm/min.	Refer to para	igraph 6
4-2-2	Terminal / Housing Retention Force	Test Speed: 25mm/min.	0.2kgf	(Min)
		Insert and withdraw actuator up to	Contact R	esistance
4-2-3	Durability	20cycles at the speed rate of less than 10 cycles/	Initial Value	\leq 20 m Ω
		minute.	Final Value	≦40 mΩ

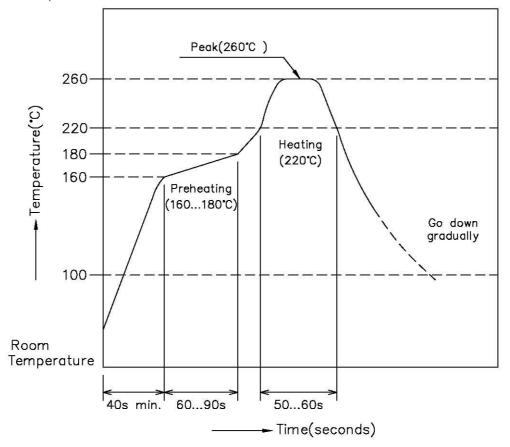
4-3 Environmental Performance and Others

	Item	Test Condition	Require	ment
		Amplitude : 1.5 mm Frequency range: 10~55~10 Hz in 1 minute	Appearance	No Damage
4-3-1	Vibration	Duration: 2 hours in each X.Y.Z axes Current: 100Ma. Test Method: MIL-STD-202F, Method 201	Contact Resistance	≤40 Mω
		Test Method. Mile-31 D-202F, Method 201	Discontinuity	1µsec
4-3-2	Heat	Temperature: 85±2°C Duration: 96 hours	Appearance	No Damage
4-0-2	Resistance	Test Method: MIL-STD-202, Method 108.	Contact Resistance	≦40 Mω
4-3-3	Cold	Temperature: -40±2°C Duration: 96 hours Test Method: JIS C60068-2-1	Appearance	No Damage
7-3-3	Resistance	rest Method. 010 00000-2-1	Contact Resistance	≦40 Mω
		Temperature: 40±2℃ Relative Humidity: 90~95%	Appearance	No Damage
4-3-4	4-3-4 Humidity	Duration: 96 hours Test Method: MIL-STD-202F , Method 103	Contact Resistance	≦40 Mω
	Trainialty		Insulation Resistance	≧40Mω
			Dielectric Strength	Must meet 4-1-3

	Item	Test Condition	Requi	rement
4-3-5	Solder Ability	Soldering Time : 3 ± 0.5 sec Solder Temperature : $245\pm5^{\circ}$ C Test Method: MIL-STD-202F , Method 208G	Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-6	Resistance To Soldering Heat	Soldering Time : 10 ± 0.5 sec Solder Temperature : $260\pm5^{\circ}$ C Test Method: MIL-STD-202F , Method 210A	Appearance	No Damage
		Steam Aging Temperature : 98±2°C Duration: 8 hours Solder Temperature : 245±5°C	Appearance	No Damage
4-3-7	Steam Aging	Soldering Time: 3±0.5 sec Test Method: MIL-STD-202F, Method 208	Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-8	Salt Spray	Chamber Temperature : $35\pm2^{\circ}$ C Air Tank Temperature : $47\pm1^{\circ}$ C Salt Solution : $5\pm0.5\%$	Appearance	No Damage
7 0 0	Can Opiay	Duration: 48 hours Test Method: MIL-STD-202, Method 101D	Contact Resistance	\leq 40 m Ω
4-3-9	Temperature	5 cycles of : a) - 55 $\pm 3^{\circ}$ C 30 minutes b) +25 $\pm 3^{\circ}$ C 30 minutes	Appearance	No Damage
∓-U-∂	Cycling	c)+ 85 \pm 2°C 30 minutes Test Method: JIS C0025	Contact Resistance	\leq 40 m Ω

5.INFRARED REFLOW CONDITION

- 1) Ascending time to preheating temperature 170°C shall be 40 seconds minimum.
- 2) Preheating shall be fixed at 160...180°C for 60...90 seconds.
- 3) Heating shall be fixed at 220°C for 50...60 seconds.
- 4) At 260±5°C peak shall be 10 seconds maximum.



ENTERY INDUSTRIAL CO., LTD. 6. 1.0mm FPC RETENTION FORCE SPEC

No of		Retention Force (MIN)		No of		Retentio	on Force IN)
CKT	UNIT	1 st	10 th	CKT	UNIT	1 st	10 th
4	Kgf	0.200	0.125	18	Kgf	0.550	0.475
5	Kgf	0.225	0.150	19	Kgf	0.575	0.500
6	Kgf	0.250	0.175	20	Kgf	0.600	0.525
7	Kgf	0.275	0.200	21	Kgf	0.625	0.550
8	Kgf	0.300	0.225	22	Kgf	0.650	0.575
9	Kgf	0.325	0.250	23	Kgf	0.675	0.600
10	Kgf	0.350	0.275	24	Kgf	0.700	0.625
11	Kgf	0.375	0.300	25	Kgf	0.725	0.650
12	Kgf	0.400	0.325	26	Kgf	0.750	0.675
13	Kgf	0.425	0.350	27	Kgf	0.775	0.700
14	Kgf	0.450	0.375	28	Kgf	0.800	0.725
15	Kgf	0.475	0.400	29	Kgf	0.825	0.750
16	Kgf	0.500	0.425	30	Kgf	0.850	0.775
17	Kgf	0.525	0.450				

FPC /FFC Connector Front Flip Lock Type Handling Precautions

This manual is to describe basic precautions. When there are doubtful points in use of, please contact E&T.

1. Common Handling Precautions

- Do not expose E&T's ZIF FPC/FFC connector, processing process product and processing product to corrosive substance, corrosive gas, high temperature and high humidity and direct sunshine. It causes corrosion of contact and deterioration of insulation performance of housing, etc., so that it causes motion defect of appliances.
- Do not apply external load to E&T's ZIF FPC/FFC connector, processing process product and processing product. Deformation and breakage, etc. occur, and it causes performance defect of.
- There may be slight differences in the housing coloring, but there will be no influence on the product's performance.
- Please add a stiffener on the flexible printed circuit (FPC/FFC) when you mount the connector onto FPC in order to prevent deformation of the FPC/FFC.
- Please do not conduct any "washing process" on the connector because it may damage the product's function.

2. PC Board Precautions

- Exercise caution when handling boards with the connectors installed. Do not apply any forces affecting soldered joints. (see figure 1).
- The mounting specification for coplanarity does not include the influence of warpage of the printed circuit board. (see figure 1).

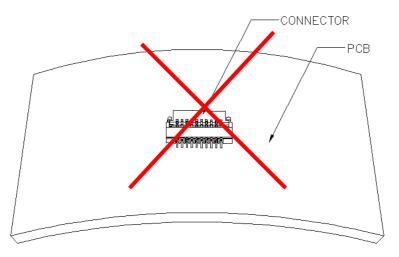


Figure 1.

3. Operation

FPC/FFC Insertion Procedure.

• 1) Connector installed on the board. Lift up the actuator(Lock). Use thumb or index finger. (see figure 2).

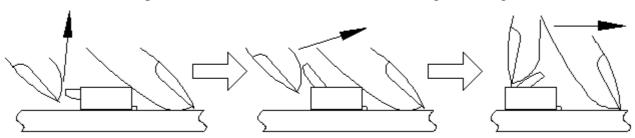


Figure 2.

• 2) Assure that the FPC/FFC is fully inserted parallel to mounting surface, with the exposed conductive traces facing down. (see figure 3).

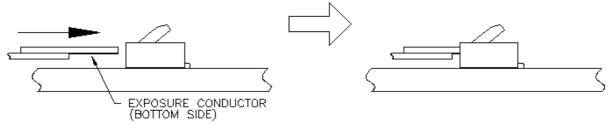


Figure 3.

• 3) Rotate down the actuator(Lock) until firmly closed. It is critical that the inserted FPC is not moved and remains fully inserted. Should the FPC be moved, open the actuator(Lock) and repeat the process, starting with Step 1(see figure 4).

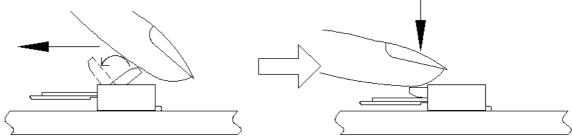


Figure 4.

FPC/FFC Removal.

10) Lift up the actuator(Lock). Carefully withdraw the FPC/FFC. (see figure 5).

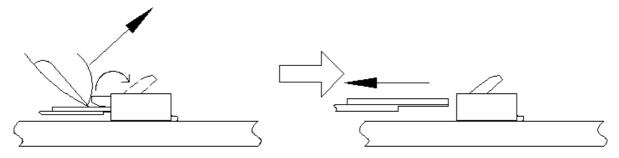


Figure 5.

4. Precautions When Inserting or Withdrawal FPC/FFC

• FPC/FFC to be insertion and withdrawal at an angle of about 15°, and the FPC/FFC should be inserted firmly all the way to the back. (see figure 6).

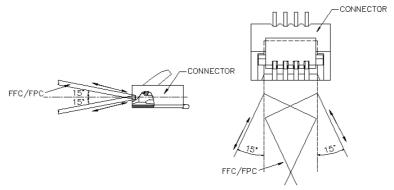


Figure 6.

- Do not apply excessive force or use any type of tool to operate the actuator(Lock).
- When locking the actuator(Lock), please make sure that the actuator is entirely closed by pressing on the entire actuator. Pushing the one specific point of the actuator may cause the actuator to be detached or damaged. When locking the longer actuator(Lock), please use two points to put pressure on locking. (see figure 7).

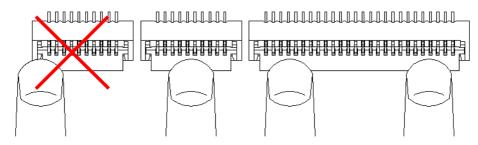
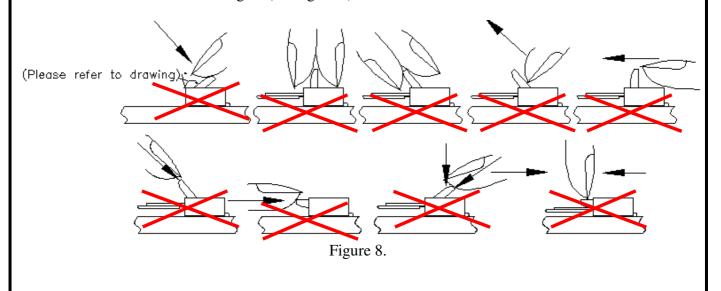


Figure 7.

- The connector will assure reliable performance when the actuator is open to an angle (please refer to drawing) maximum. Do not exceed this angle, as this may cause permanent damage to the connector. (see figure 8)
- Avoid grasping the actuator(Lock) with two fingers or lifting the actuator(Lock) with fingernail. (see figure 8)
- Do not apply force in the direction of arrows. Doing this may cause the actuator to be detached or damaged. (see figure 8).



• When inserting the FPC/FFC, do not forcefully rub against the surface beneath the connector insertion slot. Doing so will result in the FPC/FFC forcefully striking the contacts and this will cause contact deformation, peeling of the FPC/FFC conductors, and other irregularities. (see figure 9).

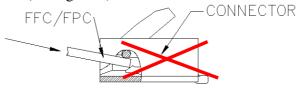
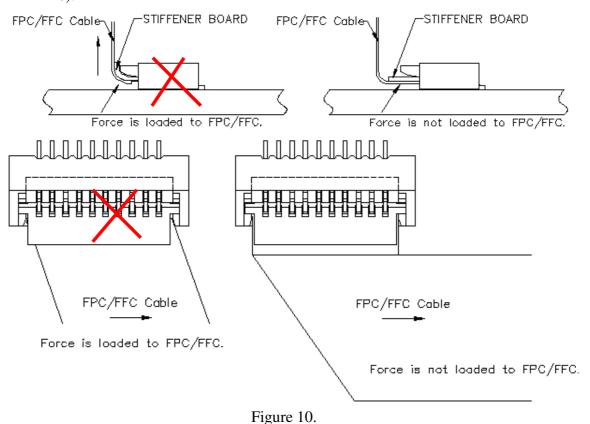


Figure 9.

- Do not apply any forces affecting soldered joints. Do not apply upward pull-force to the FPC/FFC close to the connector. (see figure 10).
- If necessary, please fix the FPC/FFC directly on the chassis. Also, please avoid pulling the FPC/FFC vertically or twisting the FPC back and force horizontally while it is inserted in the connector(see figure 10).
- Forming processing is conducted to FPC so as not to load force to connector. (see figure 10).



RELEASE HISTORY

Rev.	Revisions	Date	Executor	Description
A2	RE201108011	Aug-19-2011	Well	ADD Handling Precautions
A3	REN140206	Feb-19-2014	Juno	Modify P/N
A4	RE201305023 RE201412009 RE201503002	Apr-23-2015	Juno	Modify UL Modify P/N